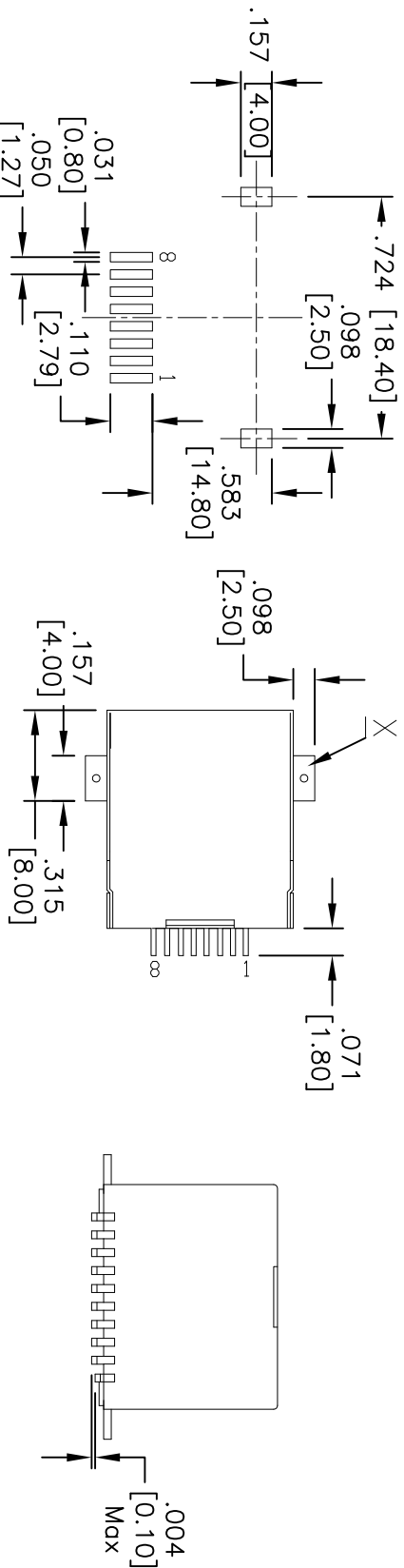
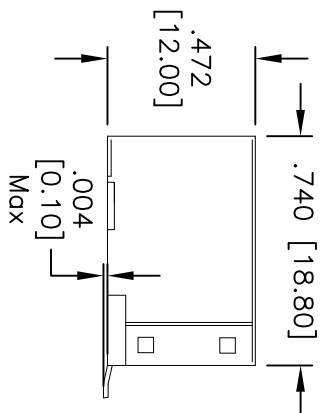
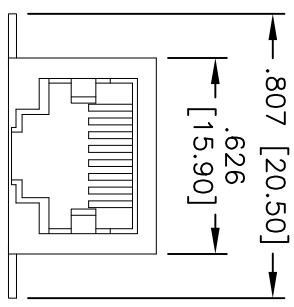


APPROVED: _____
 DATE: _____ TITLE: _____

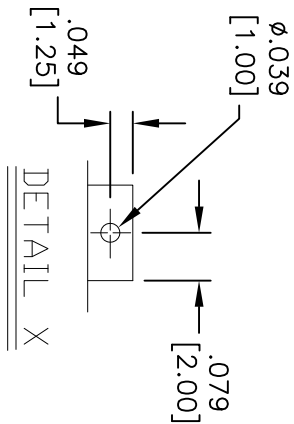
Rev	AWO #	Description	Date	Appr
-		RELEASED	1/07/09	
A		REVISED SHAPE	9/1/11	



RECOMMENDED PCB LAYOUT



X	PLATING
0	15 μ in Gold
1	30 μ in Gold
2	50 μ in Gold



SPECIFICATIONS:

Material: Insulator: Hi-temp thermoplastic, rated UL 94V-0
 Insulator color: Black
 Contacts: Phosphor Bronze
 Shield: Copper Alloy, Nickel plated
 Plating: Gold over Nickel underplate on contact area, Tin over Copper underplate on SMT tails. (See chart for thickness)
 Electrical:

Operating voltage: 150 VAC max
 Current rating: 1.5 Amps max
 Contact resistance: 20 mohms max
 Insulation resistance: 500 Mohms min @ 500 VDC
 Dielectric withstanding voltage: 1000 VAC for 1 minute
 Temperature Rating: Operating temperature: -40°C to +125°C
 Environmental: Lead free, RoHS compliant.



TITLE: MODULAR TELEPHONE JACK, 8P8C
 RIGHT ANGLE, TRUE SURFACE MOUNT

UNLESS OTHERWISE SPECIFIED
 ALL DIMENSIONS ARE INCHES [MM]
 TOLERANCES: EXCEPT AS NOTED

INCHES	HOLES
.X ± .10	ØX ± .10
.XX ± .020	ØXX ± .015
.XXX ± .015	ØXXX ± .010

APPROVALS: _____ DATE: _____

DRAWN	DY	1/07/09
CHECKED		
APPROVED		

SIZE	PART NO.	REV.
X	MTJ-88WX1-FS-TSMT	A
REF:	S00065T	SHEET 1 OF 1
SCALE:	NTS	